

**PATENT ASSIGNMENT**

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Applied Materials, Inc.	07/20/2006
RECEIVING PARTY DATA	
Name:	Sokudo Co., Ltd.
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PROPERTY NUMBERS Total: 1	
Property Type	Number
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NAME OF SUBMITTER:	Craig C. Largent

Total Attachments: 5  
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## ASSIGNMENT OF PATENTS

This ASSIGNMENT OF PATENTS (this "Assignment") granted by **Applied Materials, Inc.**, a Delaware Corporation, ("Transferor") to **Sokudo Co., Ltd.**, a Japanese *kabushiki kaisha*, ("Company") is made effective as of July 29 2006.

### RECITALS

WHEREAS, pursuant to the Master Agreement, dated May 15, 2006, by and between the Transferor and **Dainippon Screen Mfg. Co., Ltd.**, a Japan *kabushiki kaisha*, Transferor agreed to transfer to Company various intellectual property rights, including the patents and patent applications set forth on Appendix A hereto and described below; and

WHEREAS, Transferor desires to transfer and assign to Company, and Company desires to accept the transfer and assignment of, all of Transferor's worldwide right, title and interest in, to, and under such patents and patent applications;

NOW THEREFORE, for and in consideration of covenants and agreements set forth below and the Master Agreement and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged:

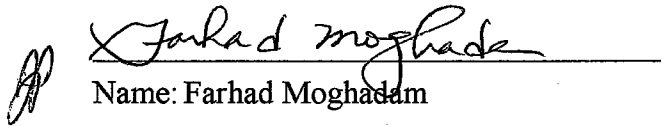
1. Transferor hereby assigns, delivers, transfers, and conveys unto Company, all right, benefits, title, and interest in and to the patents and patent applications set forth on Schedule A (collectively, the "Patents"), and all future patents which may be granted therefor throughout the world and all divisions, reissues, reexaminations, substitutions, continuations, foreign counterparts and extensions of the Patents (collectively "Future Patents"); and Transferor hereby authorizes and requests the United States Patent and Trademark Office and other patent offices throughout the world to issue all Future Patents, insofar as Transferor's interest is concerned, to Company.
2. Transferor will execute any and all powers of attorney, applications, assignments, declarations, affidavits, and any other papers in connection therewith reasonably necessary to perfect such right, benefit, title, and interest in Company.

[Signature Page Follows]

**EXECUTION VERSION  
CONFIDENTIAL**

**IN WITNESS WHEREOF**, Transferor has caused this Assignment to be executed by its duly authorized corporate officer effective as of the date first written above.

**Applied Materials, Inc.**

A handwritten signature in cursive script, appearing to read "Farhad Moghadam", is written over a horizontal line. To the left of the signature, there is a small, stylized handwritten mark that looks like "AP".

Name: Farhad Moghadam

Its: Senior Vice President,  
General Manager  
Thin Films Product Business Group  
and Foundation Engineering

**Appendix A  
Patents and Patent Applications**

<u>Title</u>	<u>U.S. Application / Patent No.</u>	<u>U.S. Filing Date</u>
Twin architecture for processing a substrate	Provisional: S/N 60/639,109	12/22/2004
Cluster tool architecture for processing a substrate	Non-Provisional: Apparatus 11/112,281; Method 11/112,932	4/22/2005
Coat/develop module with shared dispense	11/111,353	4/20/2005
Coat/develop module with independent stations	11/111,154	4/20/2005
Purged vacuum chuck with proximity pins	11/111,155	4/20/2005
Developer endpoint detection in a track lithography system	11/111,156	4/20/2005
Electrostatic chuck for track thermal plates	60/674,155 11/153974	4/21/2005 (Prov) 6/15/2005 (Non- Prov)
An integrated thermal unit having a shuttle with a temperature controlled surface	60/674,018 11/174988	4/21/2005 (Prov) 7/05/2005 (Non- Prov)
Integrated thermal unit with a shuttle having a two-axis movement	60/674,018 11/174781	4/21/2005 (Prov) 7/05/2005 (Non- Prov)
Integrated thermal unit having laterally adjacent bake and chill plates on different planes	60/674,018 11/174782	4/21/2005 (Prov) 7/05/2005 (Non- Prov)
Bake plate having engageable thermal mass	60/674,018 11/174681	4/21/2005 (Prov) 7/05/2005 (Non- Prov)
Software sequencer to dynamically adjust wafer transfer decision	60/695,262 11/436139	6/29/2005 (Prov) 5/17/06 (NonProv)
Post-exposure bake endpoint	11/147037	6/6/2005
CD measurements using molecular binding	11/207351	8/19/2005
Scalable uniform thermal plate	60/696,392 11/402,564	7/1/2005 4/12/2006
Distributed temperature control system for point of dispense temperature control	11/316329	12/21/2005
Dispense pump calibration method	11/325885	1/4/2006
Composite heater and chill plate	11/414730	4/27/2006

<u>Title</u>	<u>U.S. Application / Patent No.</u>	<u>U.S. Filing Date</u>
Track lithography system with integrated photoresist pump, filter, and buffer vessel	11/368118	3/3/2006
Marangoni dry to prevent pattern collapse	60/794663	4/24/2006 (Prov)
Passive wafer support during acceleration	11/336,471	1/20/2006
Cluster tool substrate throughput optimization	11/344,565	1/30/2006
Optimized cluster tool transfer process and collision avoidance design	11/338,323	1/23/2006
Wafer backside particle detection for track tools	11/411422	4/25/2006
Wafer bevel particle detection	11/412058	4/25/2006
Air diffuser with rapid temperature change	11/414728	4/27/2006
Immersion processing on a track	60/776079	2/22/2006 (Prov)
Method and apparatus for controlling dispense operations in a track lithography tool	11/414133	4/27/2006
Chemical dispense system with pre-filtered photolithography chemicals	11/414132	4/27/2006
Methods for monitoring and controlling dispense using a digital optical sensor	11/380910	4/28/2006
Method and system to measure flow velocity and volume	11/380913	4/28/2006
Improved integrated bake and chill plates for track	11/413960	4/28/2006
Methods for detecting photoresist dispense abnormal conditions	11/380912	4/28/2006
Method of proximity pin manufacture	11/408465	4/21/2006
Heat exchanger with multiple temperature outputs	11/414140	4/27/2006
Control scheme for cold wafer compensation	11/414138	4/27/2006
Integrated bake and chill plate	2000-514311	9/22/1998
Apparatus and methods for thermally processing a substrate	2000-106757	4/7/2000
A coater having a controllable pressurized process chamber for semiconductor processing	08/651,277 6,248,398	5/22/1996 6/19/2001
Control system and method for providing variable ramp rate operation of a thermal cycling system	09/432,286 6,313,441	11/2/1999 11/06/2001
Thermal cycling module and process using radiant heat	09/028,177 6,018,616	2/23/1998 1/25/2000
Foam-based heat exchanger with heating element	87116116 121816	9/28/1998 3/5/2001
Thermal cycling module	09/041,471 6,359,264	3/11/1998 3/19/2002
A photoresist coater	09/199,947 6,302,960	11/23/1998 10/16/2001
Apparatus and methods for handling a substrate	09/206,087 6,454,332	12/4/1998 9/24/2002

<u>Title</u>	<u>U.S. Application / Patent No.</u>	<u>U.S. Filing Date</u>
Improved heater for use in substrate processing	09/432,287 6,278,089	11/2/1999 8/21/2001
Coater having a controllable pressurized process chamber for semiconductor processing	08/651,277 6248398	5/22/1996 6/19/2001